



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN MPA-MIC/06/1991
Notification Date 08/08/2006

**Qualification of Nantong Fujitsu (China) as an
additional assembly site for lead free devices in PDIP 32 package**

MIC - MICROCONTROLLERS

Table 1. Change Identification

Product Identification (Product Family/Commercial Product)	All part numbers in PDIP 32 package
Type of change	Package assembly location change
Reason for change	Closure of ST Malta PDIP 32 assembly line
Description of the change	MCD is pleased to announce the qualification of Nantong Fujitsu (China) assembly site for our lead free devices in PDIP32. Successful completion of the qualification plan as described page 4 will allow for production of the affected devices. There are no changes to the device design or part number as a result of this change.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Country of Origin : China
Manufacturing Location(s)	

Table 2. Change Implementation Schedule

Forecasted implementation date for change	02-Nov-2006
Forecasted availability date of samples for customer	02-Nov-2006
Forecasted date for STMicroelectronics change Qualification Plan results availability	02-Aug-2006
Estimated date of changed product first shipment	02-Nov-2006

Table 3. Change Responsibility

	Name	Signature	Date
Division Product Manager	J. Nicholas		Aug.02 ,06
Division Q.A. Manager	F. Demingo		Aug.02 ,06
Division Marketing Manager	Y. Benmokhar		Aug.02 ,06

Table 4. List of Attachments

Customer Part numbers list	
Qualification Plan results	



Customer Acknowledgement of Receipt		PCN MPA-MIC/06/1991
Please sign and return to STMicroelectronics Sales Office		Notification Date 08/08/2006
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	Name:	
	Title:	
	Company:	
	Date:	
	Signature:	
Remark		
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HPC / APG / CPG.
BACK - END QUALITY ENGINEERING.

QUALIFICATION CERTIFICATE.
N° QC-67-05- HPC/MLD

Date..... 26 October 2005
Change request..... PCR 004/04
Assembly plant..... Nantong Fujitsu
Package..... PDIP 32 S 400 mils
Products..... All

Materials..... Die Attach Material: Hitachi EN 4040 / Ag
Wire: gold 1 mil
Molding compound: Sumitomo EME 6600 CS
Lead finish: pure tin plating
Lead frame: A194 SH

Assembly report..... SDIP32NT Qualification Lot for EB76*9118AAH
Date: 29 Dec 04. Name: Tim / Shi Haizhong

Construction analysis.... CA Malta HPC 03/05 CTLib 23431 Date 16 Feb 05. Name: K. Borg

Corrective actions.... 8D Report for corrective action N°NFME.Tech.0503-044 Date: 2005-03-14

Reliability report ... HPC Rel 12_05 Date: 1st June 2005 Name: Pascal MAURICE

Temporary Instruction data..... 9 lots Date: 13 September 05. Name: Anna Wuchunyan
11 lots Date: 26 October 05. Name: Anna Wuchunyan

Conclusion.....

ASSEMBLY OF PDIP 32 Shrink 400 mils
IN NANTONG FUJITSU CHINA

IS QUALIFIED

Change request N°004/04	Title: PDIP 32 S Nantong Fujitsu		Qual N°: QC-67-05-HPC/MLD
Responsability group.	Date.	Name.	Signature.
HPC . Back-End Engineering	26/10/05	Jacques FERRARA	
HPC . Back-End Quality	26/10/05	Pascal MAURICE	
MLD Quality		Francisco DEMINGO	

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